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escale Semiconductor

Data Sheet: Technical Data

An Energy Efficient Solution by Freescale

Document Number: MMA8450Q

Rev. 9.1, 04/2012



3-Axis, 8-bit/12-bit Digital Accelerometer

The MMA8450Q is a smart low-power, three-axis, capacitive micromachined accelerometer featuring 12 bits of resolution. This accelerometer is packed with embedded functions with flexible user programmable options, configurable to two interrupt pins. Embedded interrupt functions allow for overall power savings relieving the host processor from continuously polling data. The MMA8450Q's Embedded FIFO buffer can be configured to log up to 32 samples of X,Y and Z-axis 12-bit (or 8-bit for faster download) data. The FIFO enables a more efficient analysis of gestures and user programmable algorithms, ensuring no loss of data on a shared I²C bus, and enables system level power saving (up to 96% of the total power consumption savings) by allowing the applications processor to sleep while data is logged. There is access to both low pass filtered data as well as high pass filtered data, which minimizes the data analysis required for jolt detection and faster transitions. The MMA8450Q has user selectable full scales of ±2g/±4g/±8g. The device can be configured to generate inertial wakeup interrupt signals from any combination of the configurable embedded functions allowing the MMA8450Q to monitor events and remain in a low power mode during periods of inactivity.

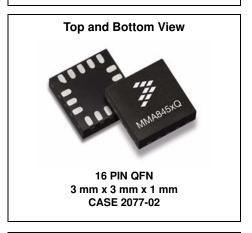
Features

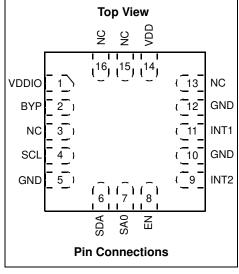
- 1.71V to 1.89V supply voltage
- ±2g/±4g/±8g dynamically selectable full-scale
- Output Data Rate (ODR) from 400 Hz to 1.563 Hz
- 375 μ g/ \sqrt{Hz} noise at normal mode ODR = 400 Hz
- 12-bit digital output
- I²C digital output interface (operates up to 400 kHz Fast Mode)
- · Programmable two interrupt pins for eight interrupt sources
- Embedded four channels of motion detection
 - Freefall or motion detection: 2 channels
 - Pulse Detection: 1 channel
 - Transient (Jolt) Detection: 1 channel
- Orientation (Portrait/Landscape) detection with hysteresis compensation
- · Automatic ODR change for auto-wake and return-to-sleep
- 32 sample FIFO
- Self-Test
- 10,000g high shock survivability
- RoHS compliant

Typical Applications

- Static orientation detection (portrait/landscape, up/down, left/right, back/front position identification)
- Real-time orientation detection (virtual reality and gaming 3D user position feedback)
- · Real-time activity analysis (pedometer step counting, freefall drop detection for HDD, dead-reckoning GPS backup)
- Motion detection for portable product power saving (auto-sleep and auto-wake for cell phone, PDA, GPS, gaming)
- Shock and vibration monitoring (mechatronic compensation, shipping and warranty usage logging)
- User interface (menu scrolling by orientation change, tap detection for button replacement

ORDERING INFORMATION						
Part Number Temperature Range Package Description Shipping						
MMA8450QT	-40°C to +85°C	QFN-16	Tray			
MMA8450QR1	-40°C to +85°C	QFN-16	Tape and Reel			









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Related Documentation

The MMA8450Q device features and operations are described in a variety of reference manuals, user guides, and application notes. To find the most-current versions of these documents:

1. Go to the Freescale homepage at:

http://www.freescale.com/

- 2. In the Keyword search box at the top of the page, enter the device number MMA8450Q.
- 3. In the Refine Your Result pane on the left, click on the Documentation link.



1 Block Diagram and Pin Description

1.1 Block Diagram

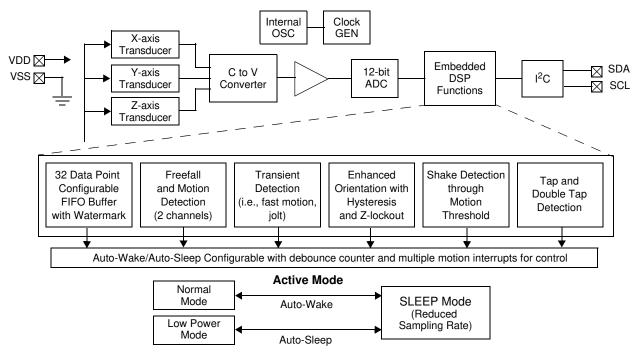


Figure 1. Block Diagram

1.2 Pin Description

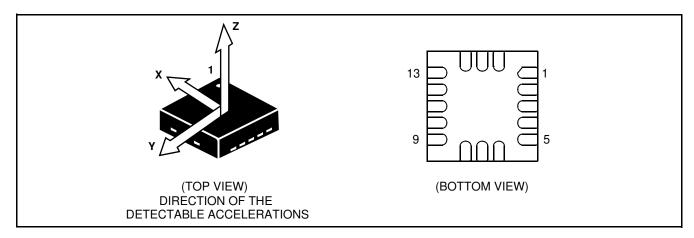


Figure 2. Direction of the Detectable Accelerations



Figure 3 shows the device configuration in the 6 different orientation modes. These orientations are defined as the following: PU = Portrait Up, LR = Landscape Right, PD = Portrait Down, LL = Landscape Left, Back and Front. There are several registers to configure the orientation detection and are described in detail in the register setting section.

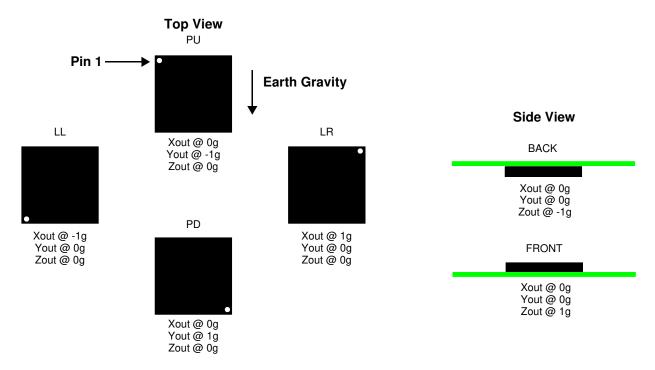


Figure 3. Landscape/Portrait Orientation

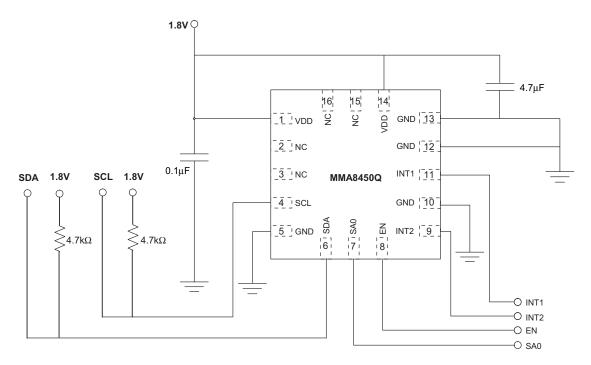


Figure 4. Application Diagram



Table 1. Pin Description

Pin#	Pin Name	Description	Pin Status
1	VDD	Power Supply (1.8 V only)	Input
2	NC/GND	Connect to Ground or Non Connection	Input
3	NC/GND	Connect to Ground or Non Connection	Input
4	SCL	I ² C Serial Clock	Open Drain
5	GND	Connect to Ground	Input
6	SDA	I ² C Serial Data	Open Drain
7	SA0	I ² C Least Significant Bit of the Device Address (0: \$1C 1: \$1D)	Input
8	EN	Device Enable	Input
	LIV	(1: I ² C Bus Enabled; 0: Shutdown Mode)	input
9	INT2	Inertial Interrupt 2	Output
10	GND	Connect to Ground	Input
11	INT1	Inertial Interrupt 1	Output
12	GND	Connect to Ground	Input
13	GND	Connect to Ground	Input
14	VDD	Power Supply (1.8 V only)	Input
15	NC	Internally not connected	Input
16	NC	Internally not connected	Input

When using MMA8450Q in applications, it is recommended that pin 1 and pin 14 (the VDD pins) be tied together. Power supply decoupling capacitors (100 nF ceramic plus 4.7 μ F bulk, or a single 4.7 μ F ceramic) should be placed as near as possible to the pins 1 and 5 of the device. The SDA and SCL I²C connections are open drain and therefore require a pullup resistor as shown in Figure 4

Note: The above application diagram presents the recommended configuration for the MMA8450Q. For information on future products of this product family please review Freescale application note, AN3923, Design Checklist and Board Mounting Guidelines of the MMA8450Q. This application note details the small modifications between the MMA8450Q and the next generation products.

1.3 Soldering Information

The QFN package is compliant with the RoHS standard. Please refer to AN4077.



2 Mechanical and Electrical Specifications

2.1 Mechanical Characteristics

Table 2. Mechanical Characteristics @ VDD = 1.8 V, T = 25°C unless otherwise noted.

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Full Scale Measurement Range	FS[1:0] set to 01		±1.8	±2	±2.2	
	FS[1:0] set to 10	FS	±3.6	±4	±4.4	g
	FS[1:0] set to 11		±7.2	±8	±8.8	
Sensitivity	FS[1:0] set to 01		0.878	0.976	1.074	
	FS[1:0] set to 10	So	1.758	1.953	2.148	mg/digit
	FS[1:0] set to 11		3.515	3.906	4.296	
Sensitivity Change vs. Temperature ⁽¹⁾	FS[1:0] set to 01	TCS ₀		±0.05		%/°C
Typical Zero-g Level Offset (2)	FS[1:0] set to 01					
	FS[1:0] set to 10	to 10 Og-Off	±40		mg	
	FS[1:0] set to 11					
Typical Zero-g Offset Post Board Mount (2), (3)	FS[1:0] set to 01			±50		
	FS[1:0] set to 10	0g-OffBM				mg
	FS[1:0] set to 11					
Typical Zero-g Offset Change vs. Temperature (2)		TCOff		±0.5		mg/°C
Non Linearity	FS[1:0] set to 01			±0.25		
Best Fit Straight Line	FS[1:0] set to 10	NL		±0.5		% FS
	FS[1:0] set to 11			±1		
Self-test Output Change ⁽⁴⁾	FS[1:0] set to 01, X-axis			-195		
	FS[1:0] set to 01, Y-axis	Vst		-195		LSB
	FS[1:0] set to 01, Z-axis			+945		
Output Noise	Normal Mode ODR = 400 Hz	Noise		375		μg/√Hz
Operating Temperature Range		Тор	-40		+85	°C

^{1.} Before board mount.

^{2.} See appendix for distribution graphs.

^{3.} Post board mount offset specification are based on an 8 layer PCB.

^{4.} Self-test in one direction only. These are approximate values and can change by ± 100 counts.



2.2 Electrical Characteristics Table 3. Electrical Characteristics @ VDD = 1.8 V, T = 25°C unless otherwise noted. (1)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
Supply Voltage		VDD	1.71	1.8	1.89	V
Low Power Mode	EN = 1, ODR = 1.563 Hz			27		
\$39 CTRL_REG2: MOD[0]=1	EN = 1, ODR = 12.5 Hz			27		μΑ
	EN = 1, ODR = 50 Hz	1		27		
	EN = 1, ODR = 100 Hz	- I _{dd} LP		42		
	EN = 1, ODR = 200 Hz	1		72		
	EN = 1, ODR = 400 Hz	1		120		
Normal Mode	EN = 1, ODR = 1.563 Hz			42		μΑ
\$39 CTRL_REG2: MOD[0]=0	EN = 1, ODR = 12.5 Hz			42		
	EN = 1, ODR = 50 Hz	1 .		42		
	EN = 1, ODR = 100 Hz	- I _{dd}		72		
	EN = 1, ODR = 200 Hz	1		132		
	EN = 1, ODR = 400 Hz			225		
Current Consumption in Shutdown Mode	EN = 0	I _{dd} Sdn		<1		μА
Supply Current Drain in Standby Mode	EN = 1 and FS[1:0] = 00	I _{dd} Stby		3		μΑ
Digital High Level Input Voltage SCL, SDA, SA0, EN		VIH	0.75*VDD			V
Digital Low Level Input Voltage SCL, SDA, SA0, EN		VIL			0.3*VDD	٧
High Level Output Voltage INT1, INT2	I _O = 500 μA	VOH	0.9*VDD			٧
Low Level Output Voltage INT1, INT2	I _O = 500 μA	VOL			0.1*VDD	٧
Low Level Output Voltage SDA	I _O = 500 μA	VOLS			0.1*VDD	٧
Output Data Rate		ODR	0.9*ODR	ODR	1.1*ODR	Hz
Signal Bandwidth		BW		ODR/2		Hz
Boot Time from EN = 1 to Boot Complete		BT		1.55		ms
Turn-on time ⁽¹⁾		Ton		3/ODR		s

^{1.} Time to obtain valid data from Standby mode to Active mode.



2.3 I²C Interface Characteristic

Table 4. I²C Slave Timing Values⁽¹⁾

Parameter	Symbol	I ² C Stand	dard Mode	Unit
Faranteter	Symbol	Min	Max	
SCL Clock Frequency				
Pullup = 1 k Ω Cb = 400 pF	$f_{\sf SCL}$	0	400	kHz
Pullup = 1 k Ω Cb = 20 pF		0	TBD	kHz
Bus Free Time between STOP and START Condition	t _{BUF}	1.3		μs
Repeated START Hold Time	t _{HD;STA}	0.6		μs
Repeated START Setup Time	t _{SU;STA}	0.6		μs
STOP Condition Setup Time	t _{SU;STO}	0.6		μs
SDA Data Hold Time ⁽²⁾	t _{HD;DAT}	50 ⁽³⁾	(4)	μs
SDA Valid Time ⁽⁵⁾	t _{VD;DAT}		0.9 ⁽⁴⁾	μs
SDA Valid Acknowledge Time ⁽⁶⁾	t _{VD;ACK}		0.9 ⁽⁴⁾	μs
SDA Setup Time	t _{SU;DAT}	100 ⁽⁷⁾		Ns
SCL Clock Low Time	t _{LOW}	4.7		μs
SCL Clock High Time	t _{HIGH}	4		μs
SDA and SCL Rise Time	t _r		1000	Ns
SDA and SCL Fall Time (3) (8) (9) (10)	t _f		300	Ns
Pulse width of spikes on SDA and SCL that must be suppressed by input filter	t _{SP}		50	Ns

- 1. All values referred to VIH (min) and VIL (max) levels.
- 2. t_{HD:DAT} is the data hold time that is measured from the falling edge of SCL, applies to data in transmission and the acknowledge.
- 3. A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the VIH (min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.
- 4. The maximum t_{HD;DAT} could be 3.45 μs and 0.9 μs for Standard-mode and Fast-mode, but must be less than the maximum of t_{VD;DAT} or t_{VD;DAT} or t_{VD;DAT} or t_{VD;DAT} by a transition time. This maximum must only be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal. If the clock stretches the SCL, the data must be valid by the setup time before it releases the clock.
- 5. t_{VD:DAT} = time for data signal from SCL LOW to SDA output (HIGH or LOW, depending on which one is worse).
- 6. t_{VD:ACK} = time for Acknowledgement signal from SCL LOW to SDA output (HIGH or LOW, depending on which one is worse).
- 7. A Fast-mode I²C device can be used in a Standard-mode I²C system, but the requirement t_{SU;DAT} 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line t_r(max) + t_{SU;DAT} = 1000 + 250 = 1250 ns (according to the Standard-mode I²C specification) before the SCL line is released. Also the acknowledge timing must meet this setup time
- 8. Cb = total capacitance of one bus line in pF.
- 9. The maximum t_f for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage t_f is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified t_f.
- 10.In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing



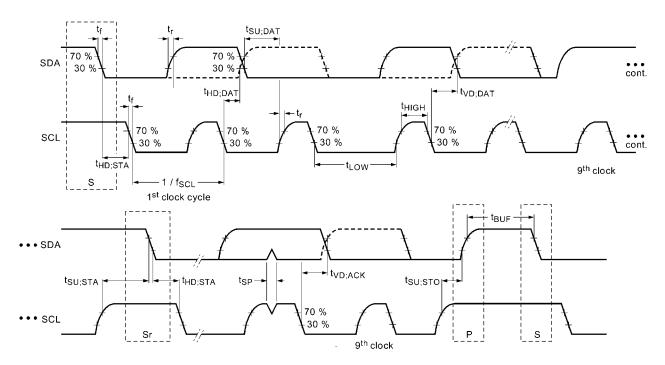


Figure 5. I²C Slave Timing Diagram

2.4 **Absolute Maximum Ratings**

Stresses above those listed as "absolute maximum ratings" may cause permanent damage to the device. Exposure to maximum rating conditions for extended periods may affect device reliability.

Table 5. Maximum Ratings

Rating	Symbol	Value	Unit
Maximum Acceleration (all axes, 100 μs)	9 _{max}	10,000	g
Supply Voltage	VDD	-0.3 to +2	V
Input voltage on any control pin (SA0, EN, SCL, SDA)	Vin	-0.3 to VDD + 0.3	V
Drop Test	D _{drop}	1.8	М
Operating Temperature Range	T _{OP}	-40 to +85	°C
Storage Temperature Range	T _{STG}	-40 to +125	°C

Table 6. ESD and Latchup Protection Characteristics

Rating	Symbol	Value	Unit
Human Body Model	НВМ	±2000	V
Machine Model	MM	±200	V
Charge Device Model	CDM	±500	V
Latchup Current at T = 85°C	<u> </u>	±100	mA



This device is sensitive to mechanical shock. Improper handling can cause permanent damage of the part or cause the part to otherwise fail.



This is an ESD sensitive, improper handling can cause permanent damage to the part.



3 Terminology

3.1 Sensitivity

Sensitivity describes the gain of the sensor and can be determined by applying a g acceleration to it, such as the earth's gravitational field. The sensitivity of the sensor can be determined by subtracting the -1g acceleration value from the +1g acceleration value and dividing by two.

3.2 Zero-g Offset

Zero-g Offset describes the deviation of an actual output signal from the ideal output signal if no acceleration is present. A sensor in a steady state on a horizontal surface will measure 0g in X-axis and 0g in Y-axis whereas the Z-axis will measure 1g. The output is ideally in the middle of the dynamic range of the sensor (content of OUT registers 0x00, data expressed as 2's complement number). A deviation from ideal value in this case is called Zero-g offset. Offset is to some extent a result of stress on the MEMS sensor and therefore the offset can slightly change after mounting the sensor onto a printed circuit board or exposing it to extensive mechanical stress.

3.3 Self-Test

Self-Test checks the transducer functionality without external mechanical stimulus. When Self-Test is activated, an electrostatic actuation force is applied to the sensor, simulating a small acceleration. In this case the sensor outputs will exhibit a change in their DC levels which are related to the selected full scale through the device sensitivity. When Self-Test is activated, the device output level is given by the algebraic sum of the signals produced by the acceleration acting on the sensor and by the electrostatic test-force.

4 Modes of Operation

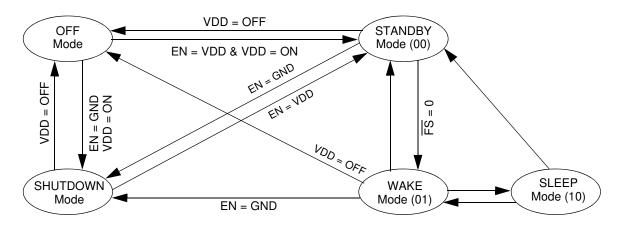


Figure 6. MMA8450Q Mode Transition Diagram

Table 7. Mode of Operation Description

Mode	I ² C Bus State	VDD	EN	Function Description
OFF	Powered Down	<1.5 V	<vdd +="" 0.3="" td="" v<=""><td>The device is powered off.</td></vdd>	The device is powered off.
SHUTDOWN	I ² C communication ignored	ON	EN = Low	All analog & digital blocks are shutdown.
STANDBY	I ² C communication possible	ON	EN = VDD Standby register set	Only POR and digital blocks are enabled. Analog subsystem is disabled. Registers accessible for Read/Write. Device configuration done in this mode.
ACTIVE	I ² C communication possible	ON	EN = VDD Standby register reset	All blocks are enabled (POR, digital, analog).

All register contents are preserved when transitioning from Active to Standby mode. Some registers are reset when transitioning from Standby to Active. These are all noted in the device memory map register table. For more detail on how to use the Sleep and Wake modes and how to transition between these modes, please refer to the functionality section of this document.



5 Functionality

The MMA8450Q is a low-power, digital output 3-axis linear accelerometer packaged in a QFN package. The complete device includes a sensing element and an IC interface able to take the information from the sensing element and to provide a signal to the external world through an I²C serial interface. There are many embedded features in this accelerometer with a very flexible interrupt routing scheme to two interrupt pins including:

- 8-bit or 12-bit data, high pass filtered data, 8-bit or 12-bit configurable 32 sample FIFO
- · Low power and Auto-Wake/Sleep for conservation of current consumption
- Single and double pulse detection 1 channel
- · Motion detection and Freefall 2 channels
- Transient detection based on a high pass filter and settable threshold for detecting the change in acceleration above a threshold
- · Flexible user configurable portrait landscape detection algorithm addressing many use cases for screen orientation

All functionality is available in 2g, 4g or 8g dynamic ranges. There are many configuration settings for enabling all the different functions. Separate application notes have been provided to help configure the device for each embedded functionality.

5.1 Device Calibration

The IC interface is factory calibrated for sensitivity and Zero-g offset for each axis. The trim values are stored in Non Volatile Memory (NVM). On power-up, the trim parameters are read from NVM and applied to the circuitry. In normal use, further calibration in the end application is not necessary. However, the MMA8450Q allows the user to adjust the Zero-g offset for each axis after power-up, changing the default offset values. The user offset adjustments are stored in 6 volatile registers. For more information on device calibration, refer to Freescale application note, AN3916.

5.2 8-bit or 12-bit Data

The measured acceleration data is stored in the OUT_X_MSB, OUT_X_LSB, OUT_Y_MSB, OUT_Y_LSB, OUT_Z_MSB, and OUT_Z_LSB registers as 2's complement 12-bit numbers. The most significant 8-bits of each axis are stored in OUT_X (Y, Z) MSB, so applications needing only 8-bit results can use these 3 registers and ignore OUT X(Y, Z) LSB.

When the full-scale is set to 2g, the measurement range is -2g to +1.999g, and each LSB corresponds to 1g/1024 (0.98 mg) at 12-bits resolution. When the full-scale is set to 8g, the measurement range is -8g to +7.996g, and each LSB corresponds to 1g/256 (3.9 mg) at 12-bits resolution. The resolution is reduced by a factor of 16 if only the 8-bit results are used. For more information on the data manipulation between data formats and modes, refer to Freescale application note, AN3922. There is a device driver available that can be used with the Sensor Toolbox demo board (LFSTBEB8450Q) with this application note.

5.3 Internal FIFO Data Buffer

MMA8450Q contains a 32 sample internal FIFO data buffer minimizing traffic across the I²C bus. The FIFO can also provide power savings of the system by allowing the host processor/MCU to go into a sleep mode while the accelerometer independently stores the data, up to 32 samples per axis. The FIFO can run at all output data rates. There is the option of accessing the full 12-bit data for accessing only the 8-bit data. When access speed is more important than high resolution the 8-bit data flush is a better option.

The FIFO contains three modes (Fill Buffer Mode, Circular Buffer Mode, and Disabled) described in the F_SETUP Register 0x13. Fill Buffer Mode collects the first 32 samples and asserts the overflow flag when the buffer is full. It does not collect anymore data until the buffer is read. This benefits data logging applications where all samples must be collected. The Circular Buffer Mode allows the buffer to be filled and then new data replaces the oldest sample in the buffer. The most recent 32 samples will be stored in the buffer. This benefits situations where the processor is waiting for an specific interrupt to signal that the data must be flushed to analyze the event.

The MMA8450Q FIFO Buffer also has a configurable watermark, allowing the processor to be interrupted after a configurable number of samples has filled in the buffer (1 to 32).

For details on the configurations for the FIFO Buffer as well as more specific examples and application benefits, refer to Freescale application note, AN3920.

5.4 Low Power Mode

The MMA8450Q can be set to a low power mode to further reduce the current consumption of the device. When the Low Power Mode is enabled, the device has access to all the configurable sampling rates and features as is available in the Normal power mode. To set the device into Low Power Mode, bit 0 in the System Control Register 2 (0x39) should be set (1) (this bit is cleared (0) for Normal Power Mode). Low Power Mode reduces the current consumption by internally sleeping longer and averaging the data less. The Low Power Mode is an additional feature that is independent of the sleep feature. The sleep feature can also be used to reduce the current consumption by automatically changing to a lower sample rate when no activity is detected.

For more information on how to configure the MMA8450Q in Low Power Mode and the power consumption benefits of Low Power Mode and Auto-Wake/Sleep with specific application examples, refer to Freescale application note, AN3921.



5.5 Auto-Wake/Sleep Mode

The MMA8450Q can be configured to transition between sample rates (with their respective current consumption) based on five of the interrupt functions of the device. The advantage of using the Auto-Wake/Sleep is that the system can automatically transition to a higher sample rate (higher current consumption) when needed but spends the majority of the time in the Sleep Mode (lower current) when the device does not require higher sampling rates. Auto-Wake refers to the device being triggered by one of the interrupt functions to transition to a higher sample rate. This may also interrupt the processor to transition from a sleep mode to a higher power mode.

Sleep Mode occurs after the accelerometer has not detected an interrupt for longer than the user definable timeout period. The device will transition to the specified lower sample rate. It may also alert the processor to go into a lower power mode to save on current during this period of inactivity.

The Interrupts that can wake the device from sleep are the following: Tap Detection, Orientation Detection, Motion/Freefall1, Motion/Freefall2, and Transient Detection. The FIFO can be configured to hold the data in the buffer until it is flushed if the FIFO Gate bit is set in Register 0x3A but the FIFO cannot wake the device from sleep.

The interrupts that can keep the device from falling asleep are the same interrupts that can wake the device with the addition of the FIFO. If the FIFO interrupt is enabled and data is being accessed continually servicing the interrupt then the device will remain in the wake mode. Refer to AN3921, for more detailed information for configuring the Auto-Wake/Sleep and for application examples of the power consumption savings.

5.6 Freefall and Motion Detection

MMA8450Q has flexible interrupt architecture for detecting Freefall and Motion with the two Motion/Freefall interrupt functions available. With two configurable interrupts for Motion and Freefall, one interrupt can be configured to detect a linear freefall while the other can be configured to detect a spin motion. The combination of these two events can be routed to separate interrupts or to the same interrupt pin to detect tumble which is the combination of spin with freefall. For details on the advantages of having the two embedded functions of Freefall and Motion detection with specific application examples with recommended configuration settings, refer to Freescale application note AN3917.

5.6.1 Freefall Detection

The detection of "Freefall" involves the monitoring of the X, Y, and Z axes for the condition where the acceleration magnitude is **below** a user specified threshold for a user definable amount of time. Normally the usable threshold ranges are between ±0 mg and ±500 mg.

5.6.2 Motion Detection

There are two programmable functions for motion (MFF1 and MFF2). Motion is configured using the high-g mechanism. Motion is often used to simply alert the main processor that the device is currently in use. When the acceleration exceeds a set threshold the motion interrupt is asserted. A motion can be a fast moving shake or a slow moving tilt. This will depend on the threshold and timing values configured for the event. The motion detection function can analyze static acceleration changes or faster jolts. For example, to detect that an object is spinning, all three axes would be enabled with a threshold detection of > 2g. This condition would need to occur for a minimum of 100 ms to ensure that the event wasn't just noise. The timing value is set by a configurable debounce counter. The debounce counter acts like a filter to determine whether the condition exists for configurable set of time (i.e., 100 ms or longer).

5.7 Transient Detection

The MMA8450Q has a built in high pass filter. Acceleration data goes through the high pass filter, eliminating the offset (DC) and low frequencies. The high pass filter cutoff frequency can be set by the user to four different frequencies which are dependent on the Output Data Rate (ODR). A higher cutoff frequency ensures the DC data or slower moving data will be filtered out, allowing only the higher frequencies to pass. The embedded Transient Detection function uses the high pass filtered data allowing the user to set the threshold and debounce counter.

Many applications use the accelerometer's static acceleration readings (i.e., tilt) which measure the change in acceleration due to gravity only. These functions benefit from acceleration data being filtered from a low pass filter where high frequency data is considered noise. However, there are many functions where the accelerometer must analyze dynamic acceleration. Functions such as tap, flick, shake and step counting are based on the analysis of the change in the acceleration. It is simpler to interpret these functions dependent on dynamic acceleration data when the static component has been removed. The Transient Detection function can be routed to either interrupt pin through bit 5 in CTRL_REG5 Register (0x3C). Registers 0x2B – 0x2E are the dedicated Transient Detection configuration registers. For details on the benefits of the embedded Transient Detection function along with specific application examples and recommended configuration settings, please refer to Freescale application note, AN3918.



5.8 Orientation Detection

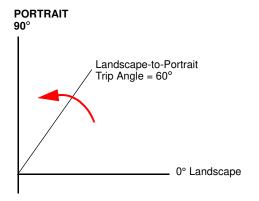
The MMA8450Q incorporates an advanced algorithm for orientation detection (ability to detect all 6 orientations including portrait/landscape) with a large amount of configuration available to provide extreme flexibility to the system designer. The configurability also allows for the function to work differently for various modes of the end system. For example, the MMA8450Q Orientation Detection allows up to 10 selectable trip angles for Portrait-to-Landscape, up to 10 selectable trip angles for the transition for Landscape-to-Portrait, and 4 selectable front/back trip angles. Typically the desired hysteresis angle is ±15° from a 45° trip reference point, resulting in |30°| and |60°| trip points. The algorithm is robust enough to handle typical process variation and uncompensated board mount offset, however, it may result in slight angle variations.

The MMA8450Q Orientation Detection algorithm confirms the reliability of the function with a configurable Z-lockout angle. Based on known functionality of linear accelerometers, it is not possible to rotate the device about the Z-axis to detect change in acceleration at slow angular speeds. The angle at which the image no longer detects the orientation change is referred to as the "Z-Lockout angle". The MMA8450Q Orientation Detection function has eight selectable1g-lockout thresholds; and there are 8 different settings for the Z-Angle lockout.

The Orientation Detection function also considers when a device is experiencing acceleration above a set threshold not typical of orientation changes (i.e., When a person is jogging or due to acceleration changes from being on a bus or in a car). The screen orientation should not interpret this as a change and the screen should lock in the last known valid position. This added feature, called the 1g Lockout Threshold, enhances the Orientation Detection function and confirms the reliability of the algorithm for the system. The MMA8450Q allows for configuring the 1g Lockout Threshold from 1g up to 1.35g (in increments of 0.05g).

For further information on the highly configurable embedded Orientation Detection Function, including recommendations for configuring the device to support various application use cases, refer to Freescale application note, AN3915.

Figure 7 and Figure 8 show the definitions of the trip angles going from Landscape-to-Portrait and then also from Portrait-to-Landscape.



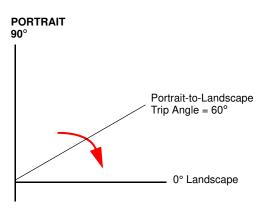


Figure 7. Illustration of Landscape-to-Portrait Transition Figure 8. Illustration of Portrait-to-Landscape Transition



Figure 9 illustrates the Z-angle lockout region. When lifting the device up from the flat position it will be active for orientation detection as low as 25° from flat. This is user configurable. The default angle is 32° but it can be set as low as 25°.

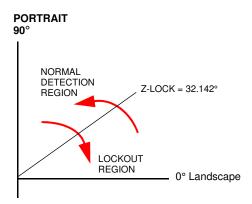


Figure 9. Illustration of Z-Tilt Angle Lockout Transition

5.9 Interrupt Register Configurations

There are eight configurable interrupts in the MMA8450Q. These are Auto-Sleep, FIFO, Transient Detect, Orientation Detect, Pulse Detect, Freefall/Motion, and the Data Ready events. These eight interrupt sources can be routed to one of two interrupt pins. The interrupt source must be enabled and configured. If the event flag is asserted because the event condition is detected, the corresponding interrupt pin, INT1 or INT2, will assert.

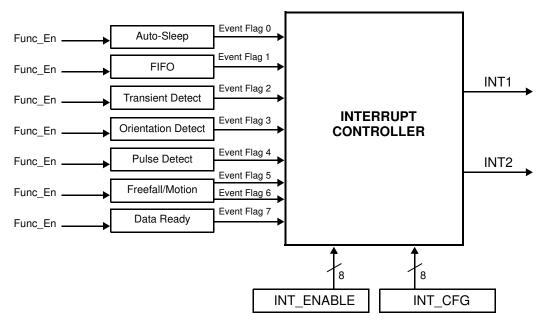


Figure 10. System Interrupt Generation Block Diagram

5.10 Serial I²C Interface

Acceleration data may be accessed through an I²C interface thus making the device particularly suitable for direct interfacing with a microcontroller. The MMA8450Q features an interrupt signal which indicates when a new set of measured acceleration data is available thus simplifying data synchronization in the digital system that uses the device. The MMA8450Q may also be configured to generate other interrupt signals accordingly to the programmable embedded functions of the device for Motion, Freefall, Transient, Orientation, and Tap.

The registers embedded inside MMA8450Q are accessed through an I^2C serial interface. The EN pin is controlled by the MCU I/O pin to be either high or low, depending on the desired state. To enable the I^2C interface, the EN pin (pin 8) must be tied high. When EN is tied low, MMA8450Q is put into low power shutdown mode and communications on the I^2C interface are ignored. The MMA8450Q is always in slave mode. The I^2C interface may be used for communications between other I^2C devices when EN is tied low and the MMA8450Q does not clamp the I^2C bus.



Table 8. Serial Interface Pin Description

Pin Name	Pin Description			
EN Device enable (1: I ² C mode enabled; 0: Shutdown mode)				
SCL	I ² C Serial Clock			
SDA	I ² C Serial Data			
SA0	I ² C least significant bit of the device address			

There are two signals associated with the I^2C bus; the Serial Clock Line (SCL) and the Serial Data line (SDA). The latter is a bidirectional line used for sending and receiving the data to/from the interface. External 4.7 k Ω pullup resistors connected to VDD are expected for SDA and SCL. When the bus is free both the lines are high. The I^2C interface is compliant with fast mode (400 kHz), and normal mode (100 kHz) I^2C standards (Table 4).



5.10.1 I²C Operation

The transaction on the bus is started through a start condition (START) signal. START condition is defined as a HIGH to LOW transition on the data line while the SCL line is held HIGH. After START has been transmitted by the Master, the bus is considered busy. The next byte of data transmitted after START contains the slave address in the first 7 bits, and the eighth bit tells whether the Master is receiving data from the slave or transmitting data to the slave. When an address is sent, each device in the system compares the first seven bits after a start condition with its address. If they match, the device considers itself addressed by the Master. The 9th clock pulse, following the slave address byte (and each subsequent byte) is the acknowledge (ACK). The transmitter must release the SDA line during the ACK period. The receiver must then pull the data line low so that it remains stable low during the high period of the acknowledge clock period.

The number of bytes transferred per transfer is unlimited. If a receiver can't receive another complete byte of data until it has performed some other function, it can hold the clock line, SCL low to force the transmitter into a wait state. Data transfer only continues when the receiver is ready for another byte and releases the data line. This delay action is called clock stretching.

A LOW to HIGH transition on the SDA line while the SCL line is high is defined as a stop condition (STOP). A data transfer is always terminated by a STOP. A Master may also issue a repeated START during a data transfer. The MMA8450Q expects repeated STARTs to be used to randomly read from specific registers.

The MMA8450Q's standard slave address is a choice between the two sequential addresses 0011100 and 0011101. The selection is made by the high and low logic level of the SA0 (pin 7) input respectively. The slave addresses are factory programmed and alternate addresses are available at customer request. The format is shown in Table 9.

Table 9. I²C Address Selection Table

Slave Address (SA0 = 0)	Slave Address (SA0 = 1)	Comment
0011100	0011101	Factory Default

Single Byte Read

The MMA8450Q has an internal ADC that can sample, convert and return sensor data on request. The transmission of an 8-bit command begins on the falling edge of SCL. After the eight clock cycles are used to send the command, note that the data returned is sent with the MSB first once the data is received. Figure 11 shows the timing diagram for the accelerometer 8-bit I²C read operation. The Master (or MCU) transmits a start condition (ST) to the MMA8450Q, slave address (\$1D), with the R/W bit set to "0" for a write, and the MMA8450Q sends an acknowledgement. Then the Master (or MCU) transmits the address of the register to read and the MMA8450Q sends an acknowledgement. The Master (or MCU) transmits a repeated start condition (SR) and then addresses the MMA8450Q (\$1D) with the R/W bit set to "1" for a read from the previously selected register. The Slave then acknowledges and transmits the data from the requested register. The Master does not acknowledge (NAK) it received the transmitted data, but transmits a stop condition to end the data transfer.

Multiple Byte Read

When performing a multibyte read or "burst read", the MMA8450Q automatically increments the received register address commands after a read command is received. Therefore, after following the steps of a single byte read, multiple bytes of data can be read from sequential registers after each MMA8450Q acknowledgment (AK) is received until a NACK is received from the Master followed by a stop condition (SP) signaling an end of transmission.

Single Byte Write

To start a write command, the Master transmits a start condition (ST) to the MMA8450Q, slave address (\$1D) with the R/W bit set to "0" for a write, the MMA8450Q sends an acknowledgement. Then the Master (MCU) transmits the address of the register to write to, and the MMA8450Q sends an acknowledgement. Then the Master (or MCU) transmits the 8-bit data to write to the designated register and the MMA8450Q sends an acknowledgement that it has received the data. Since this transmission is complete, the Master transmits a stop condition (SP) to the data transfer. The data sent to the MMA8450Q is now stored in the appropriate register.



Multiple Byte Write

The MMA8450Q automatically increments the received register address commands after a write command is received. Therefore, after following the steps of a single byte write, multiple bytes of data can be written to sequential registers after each MMA8450Q acknowledgment (ACK) is received.

Table 10. I²C device Address Sequence

Command	[6:1] Device Address	[0] SA0	[6:0] Device Address	R/W	8-bit Final Value
Read	001110	0	0x1C	1	0x39
Write	001110	0	0x1C	0	0x38
Read	001110	1	0x1D	1	0x3B
Write	001110	1	0x1D	0	0x3A

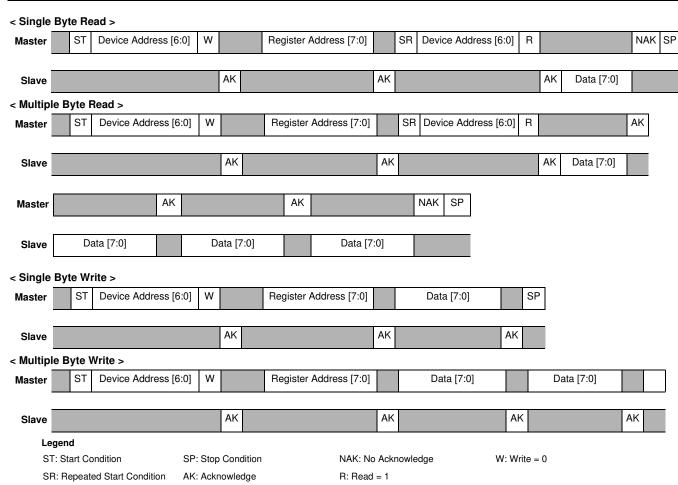


Figure 11. I²C Timing Diagram



6 Register Descriptions

Table 11 is the memory map of the MMA8450Q. The user has access to all addresses from 0x00 to 0x3F. **Note:** There are no differences between the MSBs located in 0x01, 0x02, 0x03 and 0x06, 0x08, 0x0A.

Table 11. Register Address Map

Name	Туре	Register Address		crement ress	Default	Com	ment	
STATUS ⁽¹⁾⁽²⁾	R	0x00	0x	01	00000000	Addresses 0x00, 0x04, same register. Data Rea FIFO status	dy status information or	
OUT_X_MSB ⁽¹⁾⁽²⁾	R	0x01	0x02	0x01	output	[7:0] are 8 MSBs of 12-bit real-time sample.	Root pointer to XYZ FIFO 8-bit data.	
OUT_Y_MSB ⁽¹⁾⁽²⁾	R	0x02	0x	03	output	[7:0] are 8 MSBs of 12	2-bit real-time sample	
OUT_Z_MSB ⁽¹⁾⁽²⁾	R	0x03	0x	00	output	[7:0] are 8 MSBs of 12-bit real-time sample		
STATUS ⁽¹⁾⁽²⁾	R	0x04	0x	05	00000000	Addresses 0x00, 0x04, same register. Data Rea FIFO status	dy status information or	
OUT_X_LSB ⁽¹⁾⁽²⁾	R	0x05	0x06	0x05	output	[3:0] are 4 LSBs of 12-bit sample.	Root pointer to XYZ FIFO 12-bit data.	
OUT_X_MSB ⁽¹⁾⁽²⁾	R	0x06	0x	07	output	[7:0] are 8 MSBs of 12-bit real-time sample		
OUT_Y_LSB ⁽¹⁾⁽²⁾	R	0x07	0x	08	output	[3:0] are 4 LSBs of 12-bit real-time sample		
OUT_Y_MSB ⁽¹⁾⁽²⁾	R	0x08	0x	09	output	[7:0] are 8 MSBs of 12-bit real-time sample		
OUT_Z_LSB ⁽¹⁾⁽²⁾	R	0x09	0x	0A	output	[3:0] are 4 LSBs of 12-bit real-time sample		
OUT_Z_MSB ⁽¹⁾⁽²⁾	R	0x0A	0x	04	output	[7:0] are 8 MSBs of 12-bit real-time sample		
STATUS ⁽¹⁾⁽²⁾	R	0x0B	0x	0C	00000000	Addresses 0x00, 0x04, 0x0B are aliases to the same register. Data Ready status information or FIFO status information.		
OUT_X_DELTA ⁽¹⁾⁽²⁾	R	0x0C	0x	0D	output	8-bit AC X-axis data		
OUT_Y_DELTA ⁽¹⁾⁽²⁾	R	0x0D	0x	0E	output	8-bit AC Y	-axis data	
OUT_Z_DELTA ⁽¹⁾⁽²⁾	R	0x0E	0x	0B	output	8-bit AC Z	-axis data	
WHO_AM_I ⁽¹⁾	R	0x0F	0x	C6	11000110	NVM Programmable	Fixed Device ID No.	
F_STATUS ⁽¹⁾⁽²⁾	R	0x10	0x	11	00000000	FIFO Status: No FI	FO event Detected	
F_8DATA ⁽¹⁾⁽²⁾	R	0x11	0x	11	Output	8-bit FII	O data	
F_12DATA ⁽¹⁾⁽²⁾	R	0x12	0x	12	Output	12-bit FI	FO data	
F_SETUP ⁽¹⁾⁽³⁾	R/W	0x13	0x	14	00000000	FIFO	setup	
SYSMOD ⁽¹⁾⁽²⁾	R	0x14	0x	15	Output	Current Sys	stem Mode	
INT_SOURCE ⁽¹⁾⁽²⁾	R	0x15	0x	16	Output	Interrup	t status	
XYZ_DATA_CFG ⁽¹⁾⁽⁴⁾	R/W	0x16	0x	17	00000000	Acceleration data eve	ent flag configuration	
HP_FILTER_CUTOFF ⁽¹⁾⁽³⁾	R/W	0x17	0x	18	00000000	Cutoff frequency is s	set to 4Hz @ 400Hz	
PL_STATUS ⁽¹⁾⁽²⁾	R	0x18	0x	19	00000000	Landscape/Portrai	t orientation status	
PL_PRE_STATUS ⁽¹⁾⁽²⁾	R	0x19	0x	1A	00000000	Landscape/Portrait	orevious orientation	
PL_CFG ⁽¹⁾⁽⁴⁾	R/W	0x1A	0x	1B	10000011	Landscape/Portrait configuration. 1g Lockout offset is set to default value of 1.15g. Debounce counters are clear during invalid sequence condition.		
PL_COUNT ⁽¹⁾⁽³⁾	R/W	0x1B	0x	1C	00000000	Landscape/Portrait	debounce counter	
PL_BF_ZCOMP ⁽¹⁾⁽⁴⁾	R/W	0x1C	0x	1D	00000010	Back-Front Trip threshold is ±75°. Z-Lockout angle is 32.14°		



Table 11. Register Address Map

rable in riegiote radioe					
PL_P_L_THS_REG1 ⁽¹⁾⁽⁴⁾	R/W	0x1D	0x1E	00011010	Portrait-to-Landscape Trip Angle is 30°
PL_P_L_THS_REG2 ⁽¹⁾⁽⁴⁾	R/W	0x1E	0x1F	00100010	Portrait-to-Landscape Trip Angle is 30°
PL_P_L_THS_REG3 ⁽¹⁾⁽⁴⁾	R/W	0x1F	0x20	11010100	Portrait-to-Landscape Trip Angle is 30°
PL_L_P_THS_REG1 ⁽¹⁾⁽⁴⁾	R/W	0x20	0x21	00101101	Landscape-to-Portrait Trip Angle is 60°
PL_L_P_THS_REG2 ⁽¹⁾⁽⁴⁾	R/W	0x21	0x22	01000001	Landscape-to-Portrait Trip Angle is 60°
PL_L_P_THS_REG3 ⁽¹⁾⁽⁴⁾	R/W	0x22	0x23	10100010	Landscape-to-Portrait Trip Angle is 60°
FF_MT_CFG_1 ⁽¹⁾⁽⁴⁾	R/W	0x23	0x24	00000000	Freefall/Motion1 configuration
FF_MT_SRC_1 ⁽¹⁾⁽²⁾	R	0x24	0x25	00000000	Freefall/Motion1 event source register
FF_MT_THS_1 ⁽¹⁾⁽³⁾	R/W	0x25	0x26	00000000	Freefall/Motion1 threshold register
FF_MT_COUNT_1 ⁽¹⁾⁽³⁾	R/W	0x26	0x27	00000000	Freefall/Motion1 debounce counter
FF_MT_CFG_2 ⁽¹⁾⁽⁴⁾	R/W	0x27	0x28	00000000	Freefall/Motion2 configuration
FF_MT_SRC_2 ⁽¹⁾⁽²⁾	R	0x28	0x29	00000000	Freefall/Motion2 event source register
FF_MT_THS_2 ⁽¹⁾⁽³⁾	R/W	0x29	0x2A	00000000	Freefall/Motion2 threshold register
FF_MT_COUNT_2 ⁽¹⁾⁽³⁾	R/W	0x2A	0x2B	00000000	Freefall/Motion2 debounce counter
TRANSIENT_CFG ⁽¹⁾⁽⁴⁾	R/W	0x2B	0x2C	00000000	Transient configuration
TRANSIENT_SRC ⁽¹⁾⁽²⁾	R	0x2C	0x2D	00000000	Transient event status register
TRANSIENT_THS ⁽¹⁾⁽³⁾	R/W	0x2D	0x2E	00000000	Transient event threshold
TRANSIENT_COUNT(1)(3)	R/W	0x2E	0x2F	00000000	Transient debounce counter
PULSE_CFG ⁽¹⁾⁽⁴⁾	R/W	0x2F	0x30	00000000	ELE, Double_XYZ or Single_XYZ
PULSE_SRC ⁽¹⁾⁽²⁾	R	0x30	0x31	00000000	EA, Double_XYZ or Single_XYZ
PULSE_THSX ⁽¹⁾⁽³⁾	R/W	0x31	0x32	00000000	X pulse threshold
PULSE_THSY ⁽¹⁾⁽³⁾	R/W	0x32	0x33	00000000	Y pulse threshold
PULSE_THSZ ⁽¹⁾⁽³⁾	R/W	0x33	0x34	00000000	Z pulse threshold
PULSE_TMLT ⁽¹⁾⁽⁴⁾	R/W	0x34	0x35	00000000	Time limit for pulse
PULSE_LTCY ⁽¹⁾⁽⁴⁾	R/W	0x35	0x36	00000000	Latency time for 2nd pulse
PULSE_WIND ⁽¹⁾⁽⁴⁾	R/W	0x36	0x37	00000000	Window time for 2nd pulse
ASLP_COUNT ⁽¹⁾⁽⁴⁾	R/W	0x37	0x38	00000000	Counter setting for auto-sleep
CTRL_REG1 ⁽¹⁾⁽⁴⁾	R/W	0x38	0x39	00000000	ODR = 400 Hz, Standby Mode.
CTRL_REG2 ⁽¹⁾⁽⁴⁾	R/W	0x39	0x3A	00000000	ST = Disabled, SLPE = Disabled, MODS = Normal mode.
CTRL_REG3 ⁽¹⁾⁽⁴⁾	R/W	0x3A	0x3B	00000000	IPOL, PP_OD
CTRL_REG4 ⁽¹⁾⁽⁴⁾	R/W	0x3B	0x3C	00000000	Interrupt enable register
CTRL_REG5 ⁽¹⁾⁽⁴⁾	R/W	0x3C	0x3D	00000000	Interrupt pin (INT1/INT2) map configuration
OFF_X ⁽¹⁾⁽⁴⁾	R/W	0x3D	0x3E	00000000	X-axis offset adjust
OFF_Y ⁽¹⁾⁽⁴⁾	R/W	0x3E	0x3F	00000000	Y-axis offset adjust
OFF_Z ⁽¹⁾⁽⁴⁾	R/W	0x3F	0x0F	00000000	Z-axis offset adjust
L				1	

^{1.} Register contents are preserved when transition from "ACTIVE" to "STANDBY" mode occurs.

Note: Auto-increment addresses which are not a simple increment are highlighted in **bold**. The auto-increment addressing is only enabled when device registers are read using I²C burst read mode. Therefore the internal storage of the auto-increment address is clear whenever a stop-bit is detected.

^{2.} Register contents are reset when transition from "STANDBY" to "ACTIVE" mode occurs.

^{3.} Modification of this register's contents can only occur when device is "STANDBY" mode

^{4.} Register contents can be modified anytime in "STANDBY" or "ACTIVE" mode. A write to this register will cause a reset of the corresponding internal system debounce counter.



6.1 Data Registers

The following are the data registers for the MMA8450Q. For more information on data manipulation of the MMA8450Q, refer to application note, AN3922.

0x00, 0x04, 0x0B: STATUS Registers

Alias for DR_Status (0x0B) or F_Status (0x10) (Read Only)

FDE (FIFO Data Enable Bit 7, Reg 0x16) Setting	Alias Status
FDE = 0	$0x00 = 0x04 = DR_STATUS (0x0B)$
FDE = 1	$0x00 = 0x04 = F_STATUS (0x10)$

When FDE bit found in register 0x16 (XYZ_DATA_CFG), bit 7 is cleared (the FIFO is not on) register 0x00, 0x04 and 0x0B should all be the same value and reflect the real-time status information of the X, Y and Z sample data. When FDE is set (the FIFO is on) Register 0x00, 0x04 and 0x10 will have the same value and 0x0B will reflect the status of the transient data. The aliases allow the STATUS register to be read easily before reading the current 8-bit, 12-bit, or FIFO sample data using the register address auto-incrementing mechanism.

0X00, 0X04, 0X0B STATUS: Data Status Registers (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ZYXOW	ZOW	YOW	XOW	ZYXDR	ZDR	YDR	XDR

Table 12. STATUS Description

	X, Y, Z-axis Data Overwrite. Default value: 0						
ZYXOW	0: No data overwrite has occurred						
	1: Previous X, Y, or Z data was overwritten by new X, Y, or Z data before it was read						
	Z-axis Data Overwrite. Default value: 0						
ZOW	0: No data overwrite has occurred						
	1: Previous Z-axis data was overwritten by new Z-axis data before it was read						
	Y-axis Data Overwrite. Default value: 0						
YOW	0: No data overwrite has occurred						
	1: Previous Y-axis data was overwritten by new Y-axis data before it was read						
	X-axis Data Overwrite. Default value: 0						
XOW	0: No data overwrite has occurred						
	1: Previous X-axis data was overwritten by new X-axis data before it was read						
	X, Y, Z-axis new Data Ready. Default value: 0						
ZYXDR	0: No new set of data ready						
	1: A new set of data is ready						
	Z-axis new Data Available. Default value: 0						
ZDR	0: No new Z-axis data is ready						
	1: A new Z-axis data is ready						
	Z-axis new Data Available. Default value: 0						
YDR	0: No new Y-axis data ready						
	1: A new Y-axis data is ready						
	Z-axis new Data Available. Default value: 0						
XDR	0: No new X-axis data ready						
	1: A new X-axis data is ready						

ZYXOW is set whenever a new acceleration data is produced before completing the retrieval of the previous set. This event occurs when the content of at least one acceleration data register (i.e., OUT_X, OUT_Y, OUT_Z) has been overwritten. ZYXOW is cleared when the high-bytes of the acceleration data (OUT_X_MSB, OUT_Y_MSB, OUT_Z_MSB) of all the active channels are read.

ZOW is set whenever a new acceleration sample related to the Z-axis is generated before the retrieval of the previous sample. When this occurs the previous sample is overwritten. ZOW is cleared anytime OUT Z MSB register is read.

YOW is set whenever a new acceleration sample related to the Y-axis is generated before the retrieval of the previous sample. When this occurs the previous sample is overwritten. YOW is cleared anytime OUT Y MSB register is read.

XOW is set whenever a new acceleration sample related to the X-axis is generated before the retrieval of the previous sample. When this occurs the previous sample is overwritten. XOW is cleared anytime OUT_X_MSB register is read.

ZYXDR signals that a new sample for any of the enabled channels is available. ZYXDR is cleared when the high-bytes of the acceleration data (OUT_X_MSB, OUT_Y_MSB, OUT_Z_MSB) of all the enabled channels are read.

ZDR is set whenever a new acceleration sample related to the Z-axis is generated. ZDR is cleared anytime OUT_Z_MSB register is read. In order to enable the monitoring and assertion of this bit, the ZDR bit requires the Z-axis event detection flag to be enabled (bit ZDEFE = 1 inside XYZ_DATA_CFG register).



YDR is set whenever a new acceleration sample related to the Y-axis is available. YDR is cleared anytime OUT_Y_MSB register is read. In order to enable the monitoring and assertion of this bit, the YDR bit requires the Y-axis event detection flag to be enabled (bit YDEFE = 1 inside XYZ_DATA_CFG register).

XDR is set to 1 whenever a new acceleration sample related to the X-axis is available. XDR is cleared anytime OUT_X_MSB register is read. In order to enable the monitoring and assertion of this bit, the XDR bit requires the X-axis to event detection flag to be enabled (bit XDEFE = 1 inside XYZ_DATA_CFG register).

The **ZDR** and **ZOW** flag generation requires the Z-axis event flag generator to be enabled (ZDEFE = 1) in the XYZ_DATA_CFG register.

The **YDR** and **YOW** flag generation requires the Y-axis event flag generator to be enabled (YDEFE = 1) in the XYZ_DATA_CFG register.

The **XDR** and **XOW** flag generation requires the X-axis event flag generator to be enabled (XDEFE = 1) in the XYZ_DATA_CFG register.

The **ZYXDR** and **ZYXOW** flag generation is requires the Z-axis, Y-axis, X-axis event flag generator to be enabled (ZDEFE = 1, YDEFE = 1, XDEFE = 1) in the XYZ DATA CFG register.

0x01, 0x02, 0x03: OUT MSB 8-Bit XYZ Data Registers

X, Y and Z-axis data is expressed as 2's complement numbers. The most significant 8-bits are stored together in OUT_X_MSB, OUT_Y_MSB, OUT_Z_MSB so applications needing only 8-bit results can use these registers and can ignore the OUT_X_LSB, OUT_Y_LSB, OUT_Z_LSB. The status Register 0x00, OUT_X_MSB, OUT_Y_MSB, OUT_Z_MSB are duplicated in the auto-incrementing address range of 0x00 to 0x03 to reduce reading the status followed by 8-bit axis data to a 4 byte sequence.

0x01 OUT_X_MSB: X_MSB Register (Read Only)

D. A_MOD Regis	ter (ricad Orny)					
Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
XD10	XD9	XD8	XD7	XD6	XD5	XD4
SB: Y_MSB Regis	ter (Read Only)					
Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
YD10	YD9	YD8	YD7	YD6	YD5	YD4
SB: Z_MSB Regis	ter (Read Only)					
Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ZD10	ZD9	ZD8	ZD7	ZD6	ZD5	ZD4
	Bit 6 XD10 SB: Y_MSB Regis Bit 6 YD10 SB: Z_MSB Regis Bit 6	XD10 XD9 SB: Y_MSB Register (Read Only) Bit 6 Bit 5 YD10 YD9 SB: Z_MSB Register (Read Only) Bit 6 Bit 5	Bit 6 Bit 5 Bit 4 XD10 XD9 XD8 SB: Y_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 YD10 YD9 YD8 SB: Z_MSB Register (Read Only) Bit 6 Bit 5 Bit 4	Bit 6 Bit 5 Bit 4 Bit 3 XD10 XD9 XD8 XD7 SB: Y_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 Bit 3 YD10 YD9 YD8 YD7 SB: Z_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 Bit 3 Bit 6 Bit 5 Bit 4 Bit 3	Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 XD10 XD9 XD8 XD7 XD6 SB: Y_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 YD10 YD9 YD8 YD7 YD6 SB: Z_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 Bit 3 Bit 2	Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 XD10 XD9 XD8 XD7 XD6 XD5 SB: Y_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1 YD10 YD9 YD8 YD7 YD6 YD5 SB: Z_MSB Register (Read Only) Bit 6 Bit 5 Bit 4 Bit 3 Bit 2 Bit 1

0x05 - 0x0A: OUT_MSB and OUT_LSB 12-Bit XYZ Data Registers

X, Y and Z-axis data is expressed as 2's complement numbers. The STATUS (0x04), OUT_X_LSB (0x05), OUT_X_MSB (0x06), OUT_Y_LSB (0x07), OUT_Y_MSB (0x08), OUT_Z_LSB(0x09), OUT_Z_MSB (0x0A) are stored in auto-incrementing address range of 0x04 to 0x0A to reduce reading the status followed by 12-bit axis data to 7 bytes.

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0	0	0	0	XD3	XD2	XD1	XD0
06 OUT_X_M	SB: X_MSB Regis	ster (Read Only)					
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
XD11	XD10	XD9	XD8	XD7	XD6	XD5	XD4
07 OUT_Y_L	SB: Y_LSB Regis	ter (Read Only)				•	
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
0	0	0	0	YD3	YD2	YD1	YD0
08 OUT_Y_M	SB: Y_MSB Regis	ster (Read Only)		•			
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
YD11	YD10	YD9	YD8	YD7	YD6	YD5	YD4
09 OUT_Z_L	SB: Z_LSB Regist	er (Read Only)		•			
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
^	0	0	0	ZD3	ZD2	ZD1	ZD0
0							
	ISB: Z_MSB Regi	ster (Read Only)					
	ISB: Z_MSB Regi	ster (Read Only) Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0



The sample data output registers store the current sample data if the FIFO data output register driver is disabled, but if the FIFO data output register driver is enabled, the 12 sample data output registers point to the head of the FIFO buffer which contains the previous 32 X, Y, and Z data samples. This applies for the 8-bit data and the 12-bit data.

When the FDE bit is set to logic 1, the F_8DATA (0x11) FIFO root data pointer shares the same address location as the OUT_X_MSB register (0x01); therefore all 8-bit accesses of the FIFO buffer data must use the I²C address 0x01. The F_12DATA (0x12) FIFO root data pointer shares the same address location as the OUT_X_LSB register (0x05); therefore all 12-bit accesses of the FIFO buffer data must use the I²C address 0x05. All reads to register addresses 0x02, 0x03, 0x06, 0x07, 0x08, 0x09, and 0x0A returns a value of 0x00.

0x0C - 0x0E: OUT_X_DELTA, OUT_Y_DELTA, OUT_Z_DELTA AC Data Registers

X, Y, and Z-axis 8-bit high pass filtered output data is expressed as 2's complement numbers. The data is obtained from the output of the user definable high pass filter. The data cuts out the low frequency data, which is useful in that the offset data is removed. The value of the high pass filter cutoff frequency is set in Register 0x17.

Note: The OUT_X_DELTA, OUT_Y_DELTA, OUT_Z_DELTA registers store the high pass filtered "delta data" information regardless of the state of the FIFO data output register driver bit. Register 0x0B always reflects the status of the delta data.

0x0C OUT_X_DELTA: AC X 8-Bit Data Register (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
XD7	XD6	XD5	XD4	XD3	XD2	XD1	XD0

0x0D OUT Y DELTA: AC Y 8-Bit Data Register (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
YD7	YD6	YD5	YD4	YD3	YD2	YD1	YD0

0x0E OUT_Z_DELTA: AC Z 8-Bit Data Register (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ZD7	ZD6	ZD5	ZD4	ZD3	ZD2	ZD1	ZD0

0x0F: WHO AM I Device ID Register

This register contains the device identifier which for MMA8450Q is set to **0xC6** by default. The value is factory programmed by a byte of NVM. A custom alternate value can be set by customer request.

0x0F WHO_AM_I: Device ID Register (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
1	1	0	0	0	1	1	0

6.2 32 Sample FIFO

The following registers are used to configure the FIFO. The following are the FIFO registers for the MMA8450Q. For more information on the FIFO please refer to AN3920.

0x10: F_STATUS FIFO Status Register

The FIFO Status Register is used to retrieve information about the FIFO. This register has a flag for the overflow and watermark. It also has a counter that can be read to obtain the number of samples stored in the buffer.

0x10 F_STATUS: FIFO STATUS Register (Read Only)

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ſ	F_OVF	F_WMRK_FLAG	F_CNT5	F_CNT4	F_CNT3	F_CNT2	F_CNT1	F_CNT0

Table 13. FIFO Flag Event Description

F_OVF	F_WMRK_FLAG	Event Description
0	_	No FIFO overflow events detected.
1	_	FIFO event detected; FIFO has overflowed.
_	0	No FIFO watermark events detected.
_	1	FIFO event detected; FIFO sample count is greater than watermark value.

The F_OVF and F_WMRK_FLAG flags remain asserted while the event source is still active, but the user can clear the FIFO interrupt bit flag in the interrupt source register (INT_SOURCE) by reading the F_STATUS register.

Therefore the F_OVF bit flag will remain asserted while the FIFO has overflowed and the F_WMRK_FLAG bit flag will remain asserted while the F_CNT value is greater than the F_WMRK value.



Table 14. FIFO Sample Count Description

F_CNT[5:0]	FIFO sample counter. Default value: 00_0000.
	(00_0001 to 10_0000 indicates 1 to 32 samples stored in FIFO

F_CNT[5:0] bits indicate the number of acceleration samples currently stored in the FIFO buffer. Count 000000 indicates that the FIFO is empty.

0x11: F 8DATA 8-Bit FIFO Data

F_8DATA provides access to the previous (up to) 32 samples of X, Y, and Z-axis acceleration data at 8-bit resolution. Use F_12DATA to access the same FIFO data at 12-bit resolution. The advantage of F_8DATA access is much faster download of the sample data, since it is represented by only 3 bytes per sample (OUT X MSB, OUT Y MSB, and OUT Z MSB).

All reads to address 0x01 returns the sensor sampled data in the FIFO buffer, 3 bytes per sample (one byte per axis), with the oldest samples first, in order OUT_X_MSB, OUT_Y_MSB, and OUT_Z_MSB. When all samples indicated by the FIFO_Status register have been read from the FIFO, subsequent reads will return 0x00. Since the FIFO holds a maximum of 32 samples, a maximum of 3 x 32 = 96 data bytes of samples can be read.

The FIFO will not accumulate more sample data during an access to F_8DATA until a STOP or repeated START occurs.

0x11 F 8DATA: 8-Bit FIFO Data Register Points to Register 0x01 (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
XD11	XD10	XD9	XD8	XD7	XD6	XD5	XD4

The host application should initially perform a single byte read of the FIFO status byte (address 0x10) to determine the status of the FIFO and if it is determined that the FIFO contains data sample(s), the FIFO contents can also be read from register address location 0x01 or 0x05.

0x12: F 12DATA 12-Bit FIFO Data

F_12DATA provides access to the previous (up to) 32 samples of X, Y, and Z-axis acceleration data, at 12-bit resolution. Use F_8DATA to access the same FIFO data at 8-bit resolution. The advantage of F_8DATA access is much faster download of the sample data, since it is represented by only 3 bytes per sample (OUT_X_MSB, OUT_Y_MSB, and OUT_Z_MSB).

When the FDE bit is set to logic 1, the F_12DATA FIFO root data pointer shares the same address location as the OUT_X_MSB register (0x05); therefore all 12-bit accesses of the FIFO buffer data must use the I²C register address 0x05. All reads to the register address 0x02, 0x03, 0x06, 0x07, 0x08, 0x09, and 0x0A return a value of 0x00.

All reads from address (0x05) return the sample data, oldest samples first, in order OUT_X_LSB OUT_X_MSB, OUT_Y_LSB, OUT_Y_MSB, OUT_Z_LSB, and OUT_Z_MSB. When all samples indicated by the F_Status byte have been read from the FIFO, subsequent reads will return 0x00. Since the FIFO holds a maximum of 32 samples, a maximum of 6 x 32 = 192 data bytes can be read.

The FIFO will not accumulate more sample data during an access to F 12DATA until a STOP or repeated START occurs.

0x12 F_12DATA: 12-Bit FIFO Data Register Points to Register 0x05 (Read Only)

Ī	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
ĺ	0	0	0	0	XD3	XD2	XD1	XD0

0x13: F_SETUP FIFO Setup Register

This setup register is used to configure the options for the FIFO. The FIFO can operate in 3 states which are defined in the Mode Bits. The watermark bits are configurable to set the number of samples of data to trigger the watermark event flag. The maximum number of samples is 32. For more information on the FIFO configuration refer to AN3920.

0x13 F SETUP: FIFO Setup Register (Read/Write)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
F_MODE1	F_MODE0	F_WMRK5	F_WMRK4	F_WMRK3	F_WMRK2	F_WMRK1	F_WMRK0



Table 15. F SETUP Description

BITS	Description
	FIFO buffer overflow mode. Default value: 0.
	00: FIFO is disabled.
	01: FIFO contains the most recent samples when overflowed (circular buffer). Oldest sample is discarded to
	be replaced by new sample.
	10: FIFO stops accepting new samples when overflowed.
F_MODE[1:0] ⁽¹⁾⁽²⁾⁽³⁾	11: Not Used.
	The FIFO is flushed whenever the FIFO is disabled, during an automatic ODR change (Auto-Wake/Sleep), or
	transitioning from "STANDBY" mode to "ACTIVE" mode.
	Disabling the FIFO (F_MODE = 00) resets the F_OVF, F_WMRK_FLAG, F_CNT to zero.
	A FIFO overflow event (i.e., F_CNT = 32) will assert the F_OVF flag and a FIFO sample count equal to the
	sample count watermark (i.e., F_WMRK) asserts the F_WMRK_FLAG event flag.
	FIFO Event Sample Count Watermark. Default value: 00_0000.
	These bits set the number of FIFO samples required to trigger a watermark interrupt. A FIFO watermark event
F_WMRK[5:0] ⁽²⁾	flag (F_WMK_FLAG) is raised when FIFO sample count F_CNT[5:0] value is equal to the F_ WMRK[5:0]
	watermark.
	Setting the F_WMRK[5:0] to 00_0000 will disable the FIFO watermark event flag generation.

- 1. Bit field can be written in ACTIVE mode.
- 2. Bit field can be written in STANDBY mode.
- 3. The FIFO mode (F MODE) cannot be switched between the two operational modes (01 and 10) in Active Mode.

A FIFO sample count exceeding the watermark event does not stop the FIFO from accepting new data. The FIFO update rate is dictated by the selected system ODR. In active mode the ODR is set by the DR register in the CTRL_REG1 register and when Auto-Sleep is active the ODR is set by the ASLP RATE field in the CTRL REG1 register.

When a byte is read from the FIFO buffer the oldest sample data in the FIFO buffer is returned and also deleted from the front of the FIFO buffer, while the FIFO sample count is decremented by one. It is assumed that the host application shall use the I²C multi-read transaction to empty the FIFO.

The FIFO mode can be changed while in the active state. The mode must first be disabled F_MODE = 00 then the Mode can be changed.

0x14: SYSMOD System Mode Register

The system mode register indicates the current device operating mode. Applications using the Auto-Sleep/Auto-Wake mechanism should use this register to synchronize the application with the device operating mode transitions. The system mode register also indicates the status of the NVM parity error and FIFO gate error flags.

0x14 SYSMOD: System Mode Register (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PERR	FGERR	0	0	0	0	SYSMOD1	SYSMOD0

Table 16. SYSMOD Description

	NVM Parity Error Flag Bit. Default Value: 0.			
PERR	0: No NVM parity error was detected.			
	1: NVM parity error detected.			
	FIFO Gate Error. Default value: 0.			
FGERR	0: No FIFO Gate Error detected.			
	1: FIFO Gate Error was detected.			
	System Mode. Default value: 00.			
SYSMOD	00: Standby mode			
31310100	01: Wake mode			
	10: Sleep mode			

The FIFO Gate is set in Register 0x3A for the device configured for Auto-Wake/Sleep mode to allow the buffer to preserve the data without automatically flushing. If the FIFO buffer is not emptied before the arrival of the next sample, then the FGERR bit in register 0x14 is asserted. The FGERR remains asserted as long as the FIFO buffer remains un-emptied. Emptying the FIFO buffer clears the FGERR bit.



0x15: INT_SOURCE System Interrupt Status Register

In the interrupt source register the status of the various embedded features can be determined. The bits that are set (logic '1') indicate which function has asserted an interrupt and conversely the bits that are cleared (logic '0') indicate which function has not asserted or has deasserted an interrupt. The interrupts are rising edge sensitive. The bits are set by a low to high transition and are cleared by reading the appropriate interrupt source register.

0x15 INT_SOURCE: System Interrupt Status Register (Read Only)

Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SRC_ASLP	SRC_FIFO	SRC_TRANS	SRC_LNDPRT	SRC_PULSE	SRC_FF_MT_1	SRC_FF_MT_2	SRC_DRDY

Table 17. INT_SOURCE Description

INT_SOURCE	Description Description
	Auto-Sleep/Wake interrupt status bit
	Logic '1' indicates that an interrupt event that can cause a "Wake-to-Sleep" or "Sleep-to-Wake" system mode transition has occurred.
	Logic '0' indicates that no "Wake-to-Sleep" or "Sleep-to-Wake" system mode transition interrupt event has occurred.
SRC_ASLP	"Wake-to-Sleep" transition occurs when no interrupt occurs for a time period that exceeds the user specified limit (ASLP_COUNT). This causes the system to transition to a user specified low ODR setting.
	"Sleep-to-Wake" transition occurs when the user specified interrupt event has woken the system; thus causing the
	system to transition to a user specified high ODR setting.
	Reading the SYSMOD register clears the SRC_ASLP bit. FIFO interrupt status bit
	Logic '1' indicates that a FIFO interrupt event such as an overflow event or watermark has occurred. Logic '0' indicates
000 5150	that no FIFO interrupt event has occurred.
SRC_FIFO	FIFO interrupt event generators: FIFO Overflow, or (Watermark: F_CNT = F_WMRK) and the interrupt has been enabled.
	This bit is cleared by reading the F_STATUS register. Transient interrupt status bit
	Logic '1' indicates that an acceleration transient value greater than user specified threshold has occurred. Logic '0'
SRC_TRANS	indicates that no transient event has occurred.
ONO_ITIANO	This bit is asserted whenever "EA" bit in the TRANS_SRC is asserted and the interrupt has been enabled.
	This bit is cleared by reading the TRANS_SRC register.
	Landscape/Portrait Orientation interrupt status bit
	Logic '1' indicates that an interrupt was generated due to a change in the device orientation status. Logic '0' indicates
SRC LNDPRT	that no change in orientation status was detected.
	This bit is asserted whenever "NEWLP" bit in the PL_STATUS is asserted and the interrupt has been enabled.
	This bit is cleared by reading the PL_STATUS register.
	Pulse interrupt status bit
	Logic '1' indicates that an interrupt was generated due to single and/or double pulse event. Logic '0' indicates that no
SRC_PULSE	pulse event was detected.
	This bit is asserted whenever "EA" bit in the PULSE_SRC is asserted and the interrupt has been enabled.
	This bit is cleared by reading the PULSE_SRC register.
	Freefall/Motion1 interrupt status bit
	Logic '1' indicates that the Freefall/Motion1 function interrupt is active.
SRC_FF_MT_1	Logic '0' indicates that no Freefall or Motion event was detected.
0110_11_W11_1	This bit is asserted whenever "EA" bit in the FF_MT_SRC_1 register is asserted and the FF_MT interrupt has been enabled.
	This bit is cleared by reading the FF_MT_SRC_1 register.
	Freefall/Motion2 interrupt status bit
	Logic '1' indicates that the Freefall/Motion2 function interrupt is active.
SRC_FF_MT_2	Logic '0' indicates that no Freefall or Motion event was detected.
0110_11 _W1_2	This bit is asserted whenever "EA" bit in the FF_MT_SRC_2 register is asserted and the FF_MT interrupt has been enabled.
	This bit is cleared by reading the FF_MT_SRC_2 register.
	Data Ready interrupt bit status
SRC_DRDY	Logic '1' indicates that the X,Y,Z data ready interrupt is active indicating the presence of new data and/or data overrun Otherwise if it is a logic '0' the X,Y,Z interrupt is not active.
	This bit is asserted when the ZYXOW and/or ZYXDR is set and the interrupt has been enabled.
	This bit is cleared by reading the STATUS and X, Y, or Z register.